

Abstract of the Disclosure

A method of dry etching a PCMO stack, includes preparing a substrate; depositing a barrier layer; depositing a bottom electrode; depositing a PCMO thin film; depositing a top electrode; depositing a hard mask layer; applying photoresist and patterning; etching the hard mask layer; dry etching the top electrode; dry etching the PCMO layer in a multi-step etching process; dry etching the bottom electrode; and completing the PCMO-based device.

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